

OL-NX5P1000

WLCSP12: wafer level chip-scale package; 12 bumps

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	29-3-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.63	-	1.66	1.69	mm
E	package width		1.33	-	1.36	1.39	mm
A	seated height		0.47	-	0.51	0.55	mm
A ₂	package height		0.29	-	0.31	0.34	mm
e	nominal pitch		-	-	0.4	-	m
n ₂	actual quantity of termination		-	-	12	-	



2. Package outline

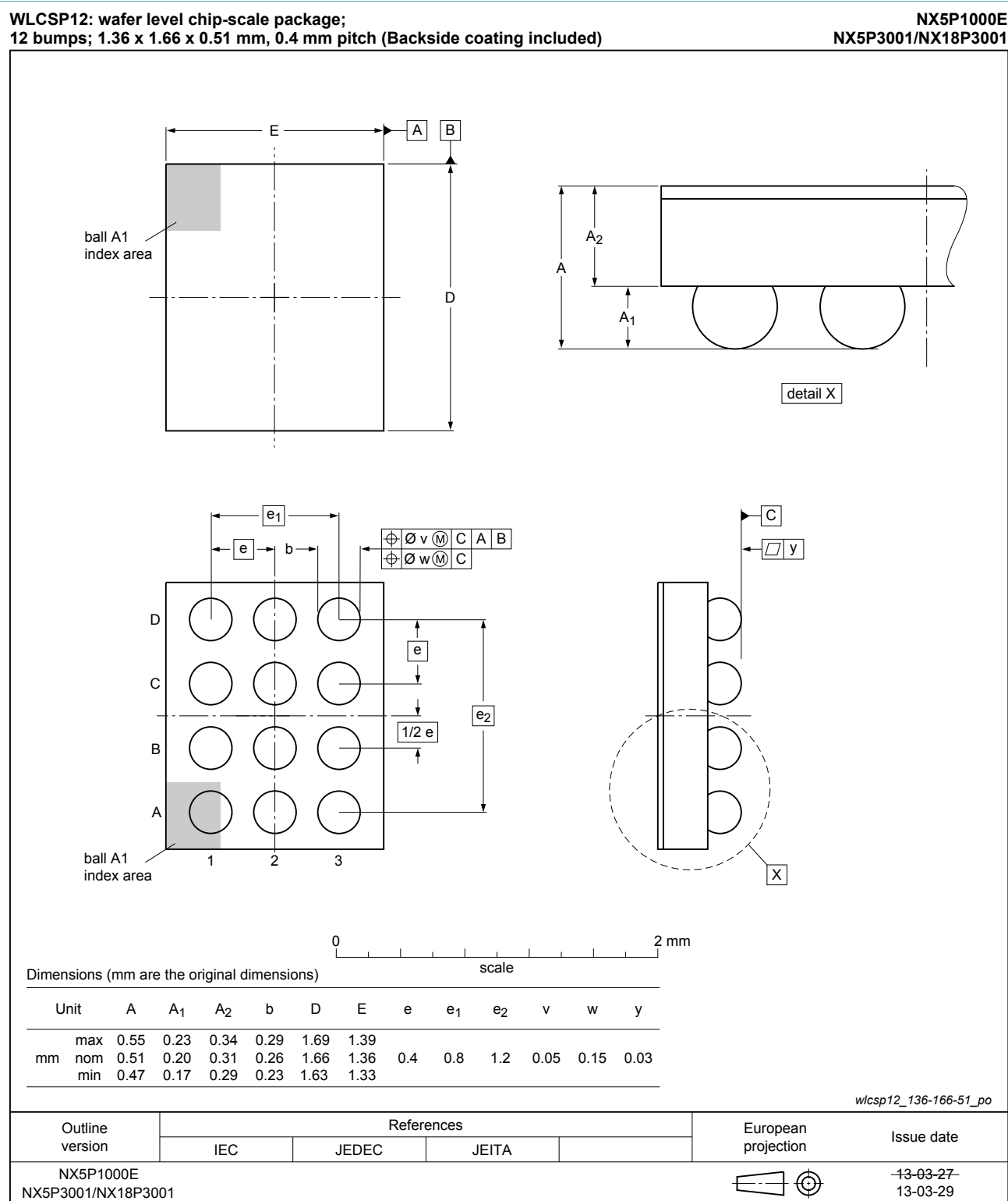


Fig. 1. Package outline WLCSP (OL-NX5P1000)

3. Legal information

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